

30V N-channel enhancement mode MOSFET

General Description

The PAN3080L is a 30V N-channel enhancement mode MOSFET which uses advanced trench technology to provide excellent $R_{DS(on)}$, low gate charge. This device is suitable for use in UPS, power switching and general purpose applications. PAN3080L is packaged in TO-252-2L package.

Features

- $V_{DS(max)} = 30V$
- $I_D(max) = 80A$
- Extremely Low $R_{DS(on)}$:
Typ. $R_{DS(on)} = 4.0\ m\Omega @ V_{GS} = 10\ V, I_D = 40\ A$
- Good stability and uniformity
- 100% avalanche tested
- Excellent package for good heat dissipation

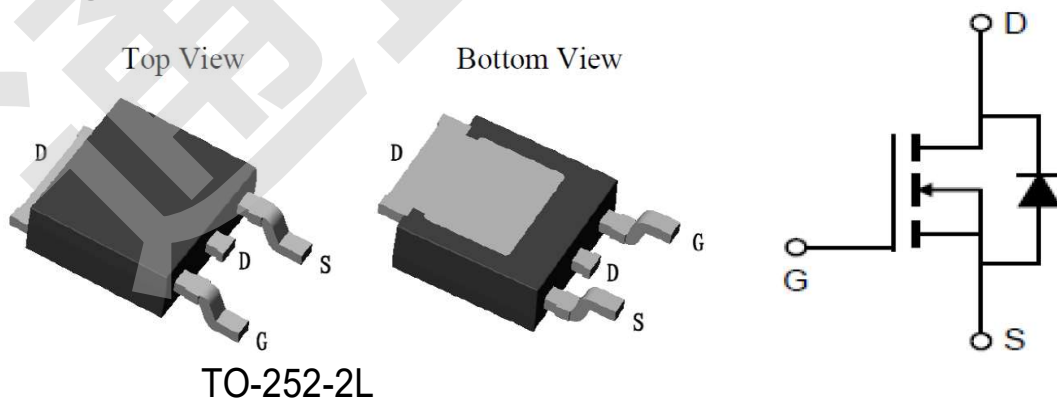
Applications

- Multi-cell Battery protection
- Battery Powered Systems
- UPS
- Portable Power Equipment

Ordering Information

Device	Package	Pin count	Marking
PAN3080L	TO-252-2L	3	PAN3080L

Pin Configurations



Main Parameters

Symbol	Parameter	Value	Units
V_{DS}	Drain-Source Voltage	30	V
I_D	Drain Current - Continuous (TC= 25°C) - Continuous (TC= 100°C)	80	A
		52*	A
I_{DM}	Drain Current - Pulsed (Note 1)	320*	A
V_{GS}	Gate-Source Voltage	± 20	V
E_{AS}	Single Pulsed Avalanche Energy (Note 2)	102	mJ
P_D	Power Dissipation (TC = 25°C) - Derate above 25°C	80	W
		0.53	W/°C
T_J, T_{stg}	Operating and Storage Temperature Range	-55 to +175	°C

* Drain current limited by maximum junction temperature

Thermal Characteristics

Symbol	Parameter	Value	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	1.63	°C/W

Electrical Characteristics TC = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\mu\text{A}$	30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 30\text{ V}, V_{GS} = 0\text{ V}$			1	μA
I_{GSSF}	Gate Leakage Current, Forward	$V_{GS} = 20\text{ V}, V_{DS} = 0\text{ V}$			100	nA
I_{GSSR}	Gate Leakage Current, Reverse	$V_{GS} = -20\text{ V}, V_{DS} = 0\text{ V}$			-100	nA
On Characteristics						
$V_{GS(TH)}$	Gate Threshold voltage	$V_{DS} = V_{GS}, I_D = 250\text{ uA}$	1	1.6	2.5	V
$R_{DS(on)}$	Drain-Source on-state resistance	$V_{GS} = 10\text{ V}, I_D = 40\text{ A}$		4.0	5.0	mΩ
		$V_{GS} = 4.5\text{ V}, I_D = 24\text{ A}$		6.9	8.6	mΩ
g_{FS}	Forward Transconductance	$V_{DS} = 5\text{ V}, I_D = 24\text{ A}$ (Note 3)	20			S
Dynamic Characteristics						

C_{iss}	Input capacitance	$V_{DS}=15V, V_{GS}=0V,$ $F=1.0MHz$		1560		pF
C_{oss}	Output capacitance			246		pF
C_{rss}	Reverse transfer capacitance			225		pF
Switching Characteristics						
$t_{d(on)}$	Turn On Delay Time	$V_{DD}=15V, I_D=20A,$ $V_{GS}=10V, R_g=30\Omega$ (Note 3, 4)		3.2		ns
t_r	Rising Time			19.6		ns
$t_{d(off)}$	Turn Off Delay Time			29.2		ns
t_f	Fall Time			18.5		ns
Q_g	Total Gate Charge	$V_{DD}=15V, I_D=45A,$ $V_{GS}=10V$ (Note 3, 4)		33.7		nC
Q_{gs}	Gate-Source Charge			4.5		nC
Q_{gd}	Gate-Drain Charge			7.4		nC
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain-Source Diode Forward Current			80		A
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current			320		A
V_{SD}	Diode Forward Voltage	$V_{GS}=0V, I_S=24A$		1.2		V
T_{rr}	Reverse recovery time	$I_F=20A, di/dt=100A/\mu S$		28		ns
Q_{rr}	Reverse recovery charge			13		nC


NOTE:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. $L = 0.5\text{ mH}, I_{AS} = 35\text{ A}, V_{DD} = 15\text{ V}, R_g = 25\ \Omega, \text{ Starting } T_j = 25^\circ\text{C}$
3. $I_{SD} \leq 40\text{ A}, di/dt = 100\text{ A}/\mu\text{s}, V_{DD} \leq BVDSS, \text{ Starting } T_j = 25^\circ\text{C}$
4. Pulse Test : Pulse width $\leq 300\mu\text{s}$, Duty cycle $\leq 2\%$
5. Essentially independent of operating temperature

Typical Characteristics and Thermal Characteristics (Curves)

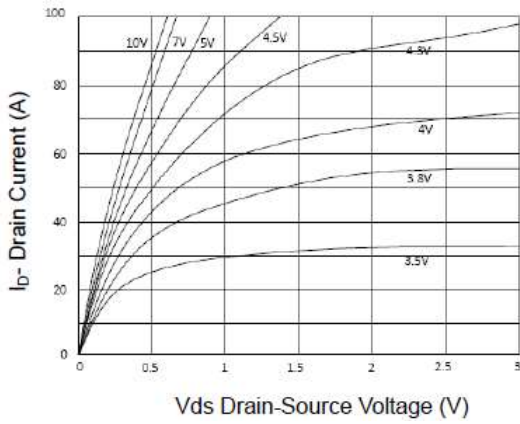


Figure 1 Output Characteristics

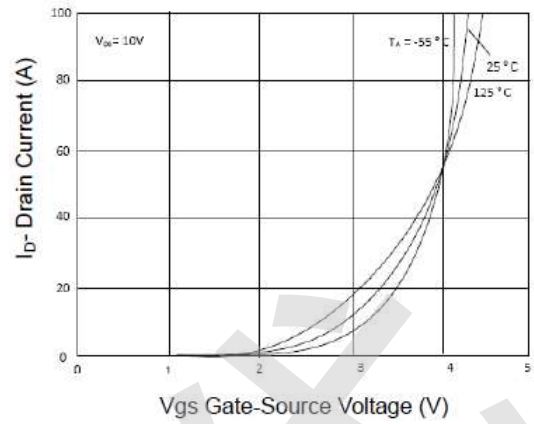


Figure 2 Transfer Characteristics

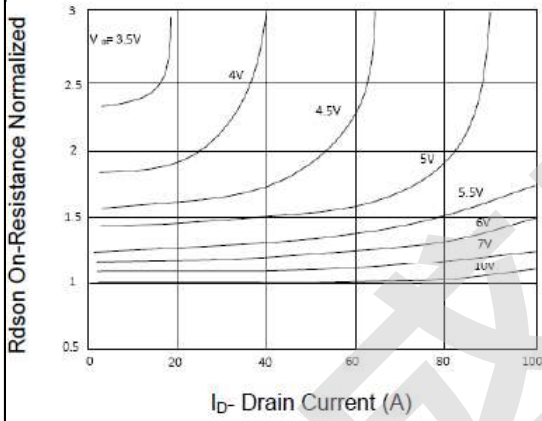


Figure 3 Rdson- Drain Current

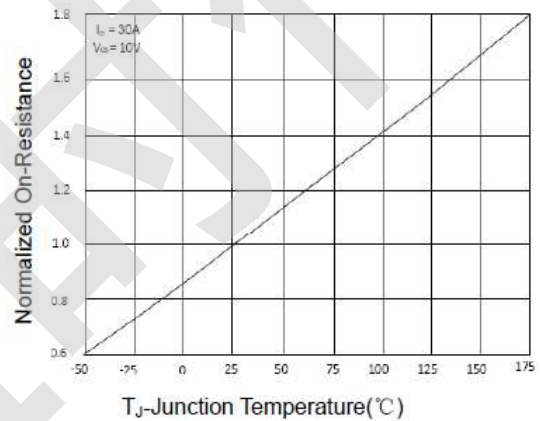


Figure 4 Rdson-Junction Temperature

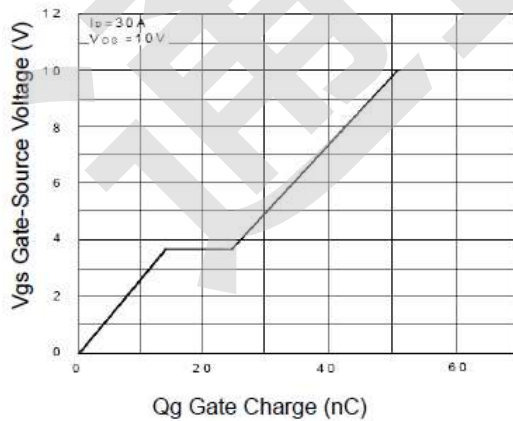


Figure 5 Gate Charge

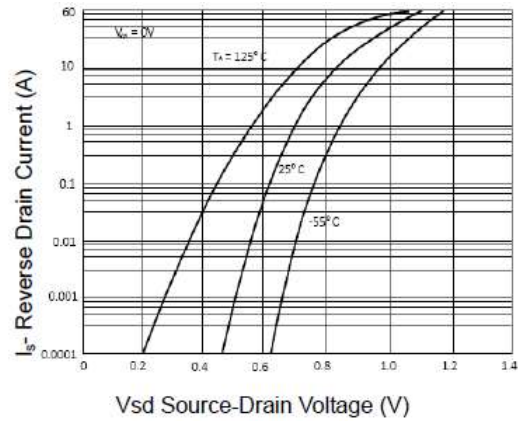


Figure 6 Source- Drain Diode Forward

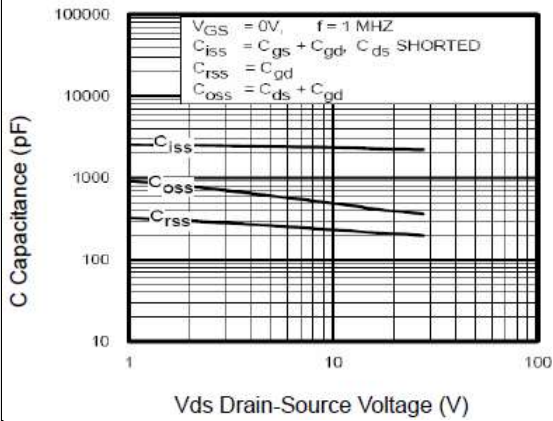


Figure 7 Capacitance vs Vds

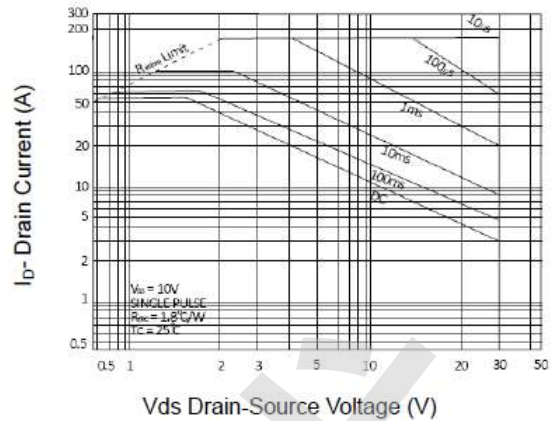


Figure 8 Safe Operation Area

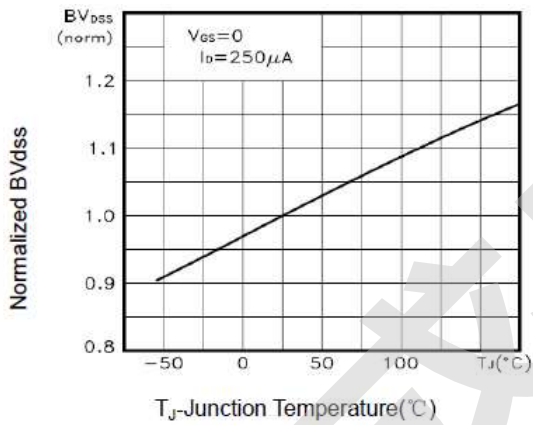


Figure 9 BVdss vs Junction Temperature

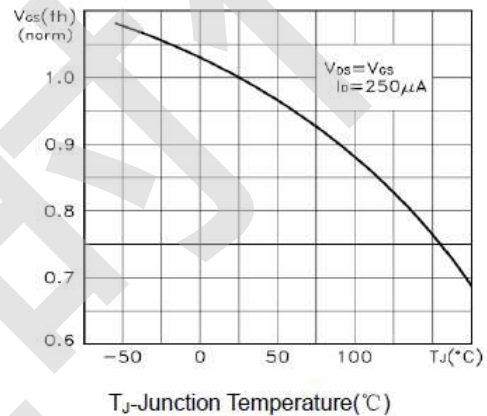


Figure 10 VGS(th) vs Junction Temperature

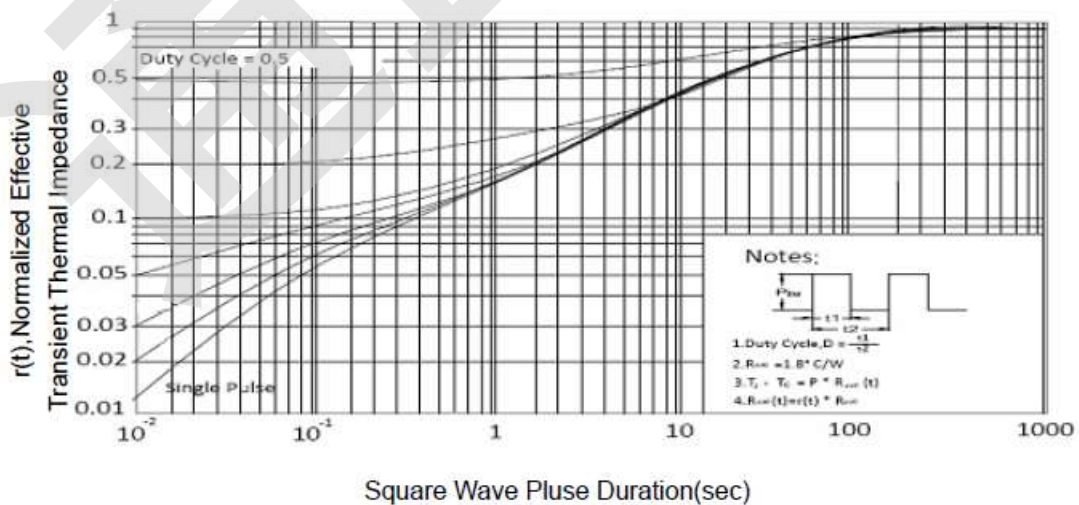
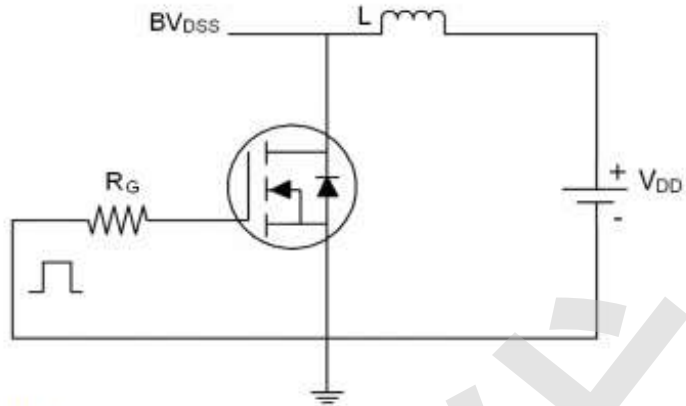


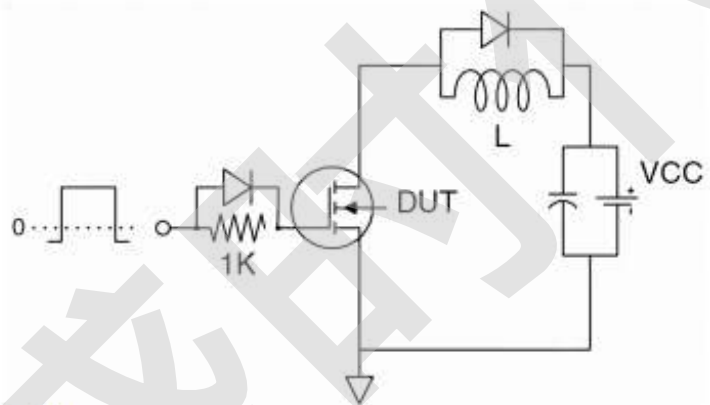
Figure 11 Normalized Maximum Transient Thermal Impedance

Test Circuit

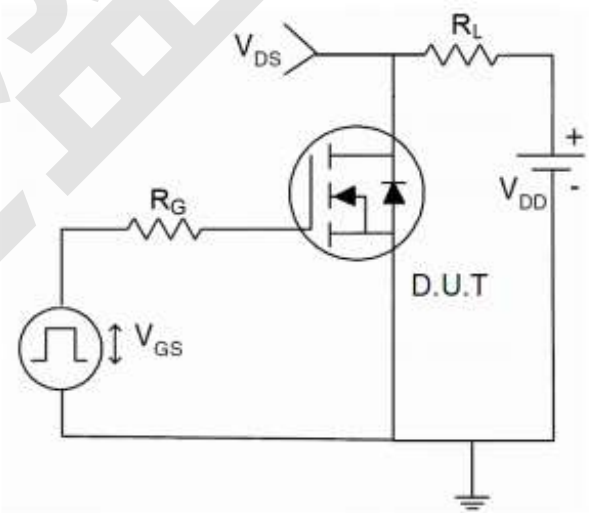
1) E_{AS} Test Circuits

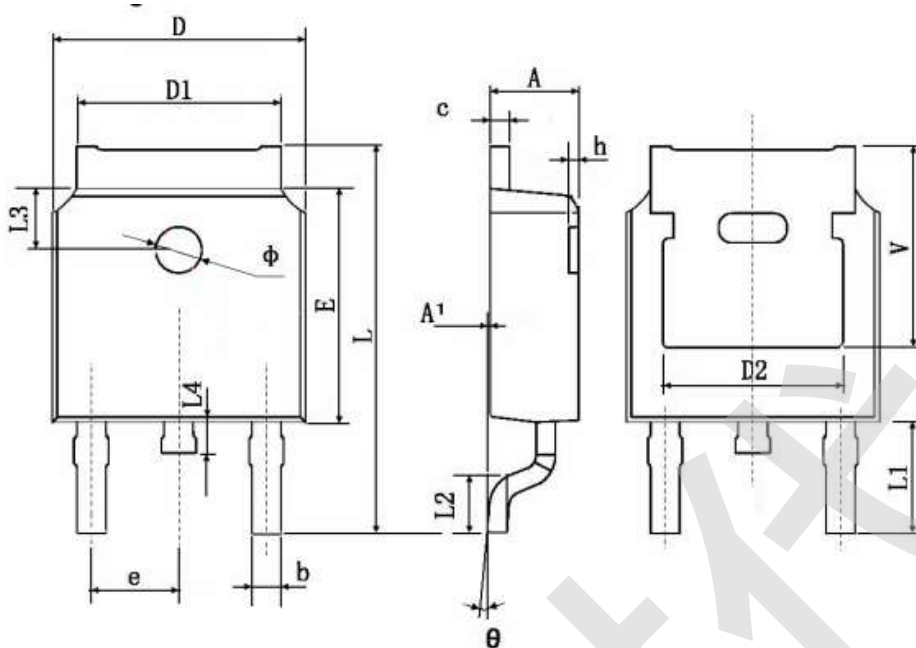


2) Gate Charge Test Circuit:



3) Switch Time Test Circuit:



Package Dimensions

TO-252-2L

SYMBOL	DIMENSIONS IN MILLIMETERS		DIMENSIONS IN INCHES	
	MIN.	MAX.	MIN.	MAX.
A	2.250	2.350	0.089	0.093
A1	0.050	0.150	0.002	0.006
B	0.660	0.860	0.026	0.034
C	0.458	0.558	0.018	0.022
D	6.550	6.650	0.259	0.263
D1	5.234	5.434	0.207	0.215
D2	4.826 TYP.		0.191 TYP.	
E	6.050	6.150	0.239	0.243
E	2.236	2.336	0.088	0.092
L	9.820	10.220	0.388	0.404
L1	3.000 TYP.		0.119 TYP.	
L2	1.400	1.600	0.055	0.063
L3	1.800 TYP.		0.071 TYP.	
L4	0.700	0.900	0.028	0.036
Φ	1.150	1.250	0.045	0.049



PAN3080L

Θ	0°	3°	0°	3°
H	0.000	0.300	0.000	0.012
V	5.399 TYP		0.213 TYP	

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